

be assembled for use with a variety of industry standard integrated circuit boards from a single kit. The cooling system is assembled by selecting the appropriate cooling attachments based on the space available on the integrated circuit board and the particular thermal situation. The kit also allows the cooling system to be added after the chassis is assembled.

IN THE CLAIMS

Please substitute the claim set in the appendix entitled Clean Version of Pending Claims for the previously pending claim set. The substitute claim set is intended to reflect amendment of previously pending claims 2, 20, 23, 25, and 26, and no addition or cancellation of claims. The specific amendments to individual claims are detailed in the following marked up set of claims.

2. (Amended) The apparatus of claim 1 further comprising an air duct coupled to the second end of the housing, the air duct to direct the flow of air from an exterior of a chassis to the housing.

20. (Amended) A method of assembling a cooling system for an integrated circuit, the method comprising:

closely coupling a housing to a heat sink for an integrated circuit; and
coupling a fan to the housing.

23. (Amended) The method of claim 22 further comprising coupling a cooling attachment to the fan.[23.]

25. (Amended) A method of cooling an integrated circuit, the method comprising:
generating a flow of external ambient air through an air duct to a housing fitted closely over a first heat sink; and
drawing the flow of external ambient air over the first heat sink.